

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>John Chen</td><td>03/24/2005</td></tr><tr><td>Hanming Wu</td><td>03/24/2005</td></tr><tr><td>Da Wei Gao</td><td>04/08/2005</td></tr><tr><td>Bei Zhu</td><td>02/13/2007</td></tr><tr><td>Paolo Bonfanti</td><td>03/24/2005</td></tr></tbody></table>	Name	Execution Date	John Chen	03/24/2005	Hanming Wu	03/24/2005	Da Wei Gao	04/08/2005	Bei Zhu	02/13/2007	Paolo Bonfanti	03/24/2005	
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RECEIVING PARTY DATA													
<table border="1"><tr><td>Name:</td><td>Semiconductor Manufacturing International (Shanghai) Corporation</td></tr><tr><td>Street Address:</td><td>18 Zhang Jiang Road, Pudong New Area</td></tr><tr><td>City:</td><td>Shanghai</td></tr><tr><td>State/Country:</td><td>CHINA</td></tr><tr><td>Postal Code:</td><td>201203</td></tr></table>	Name:	Semiconductor Manufacturing International (Shanghai) Corporation	Street Address:	18 Zhang Jiang Road, Pudong New Area	City:	Shanghai	State/Country:	CHINA	Postal Code:	201203			
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
Fax Number: (415)576-0300 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
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ATTORNEY DOCKET NUMBER:	021653-015200US												
NAME OF SUBMITTER:	Richard T. Ogawa												

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PATENT
REEL: 019044 FRAME: 0488

Total Attachments: 3

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PATENT

REEL: 019044 FRAME: 0489

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, John Chen of 18 Zhang Jiang Rd., Pudong New Area, Shanghai 201203, China; Hanming Wu of 18 Zhang Jiang Rd., Pudong New Area, Shanghai 201203, China; Da Wei Gao of 18 Zhang Jiang Rd., Pudong New Area, Shanghai 201203, China; Bei Zhu of 18 Zhang Jiang Rd., Pudong New Area, Shanghai 201203, China, and Paolo Bonfanti of 18 Zhang Jiang Rd., Pudong New Area, Shanghai 201203, China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: AN ETCHING METHOD AND STRUCTURE USING A
HARD MASK FOR STRAINED SILICON MOS
TRANSISTORS

Date(s) of execution of Declaration:

Filing Date:

Application No.: ; and

WHEREAS, Semiconductor Manufacturing International (Shanghai) Corporation, a corporation of Peoples' Republic of China, located at 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203 China, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

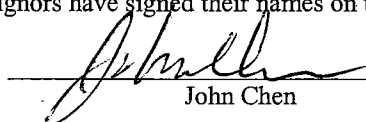
For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, Eighth Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: 3/24/2005


John Chen

Assignment

Attorney Docket No.: 021653-015200US

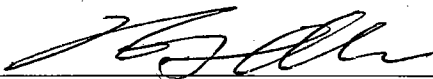
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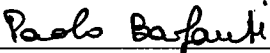
Dated:

Dated:


Hanming Wu


Da Wei Gao


Bei Zhu


Paolo Bonfanti

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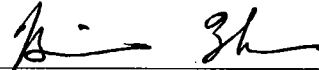
Dated: _____

Hanming Wu

Dated: _____

Da Wei Gao

Dated: 2/13/2007


Bei Zhu

Dated: _____

Paolo Bonfanti

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